

# MICA - M & P SHEETS

Technical Data	Muscovite	Phlogopite
Mica Content: (IEC 60371-2)	85 – 90 %	85 – 90 %
Silicone Binder Content: (IEC 60371-2)	10 – 15 %	10 – 15 %
Density: (IEC 60371-2)	2,2 – 2,3 g/cm <sup>3</sup>	2,2 – 2,3 g/cm <sup>3</sup>
Heat Resistance:	In Continuous Service: 500 °C In Intermittent Service: 800 °C	In Continuous Service: 700 °C In Intermittent Service: 1.000 °C
Tensile Strength: (ISO 527)	150 N/mm <sup>2</sup>	110 N/mm <sup>2</sup>
Bending Strength: (ISO 178)	230 N/mm <sup>2</sup>	170 N/mm <sup>2</sup>
Water Absorption:	<1 % (24h/23°C)	<1 % (24h/23°C)
Dielectric Strength: (IEC 60243)	at 20°C: 25 KV/mm at 400°C: 13 KV/mm at 600°C: 10 KV/mm	at 20°C: 25 KV/mm at 400°C: 13 KV/mm at 600°C: 10 KV/mm
Volume Resistivity: (IEC 60093)	at 20°C: >1016 Ω/cm >1016 Ω/cm at 400°C: >1012 Ω/cm >1012 Ω/cm at 500°C: >109 Ω/cm >109 Ω/cm	at 20°C: >1016 Ω/cm at 400°C: >1012 Ω/cm at 500°C: >109 Ω/cm
Weight Loss Continuous: (IEC 60371-2)	at 500°C: <1 %	at 500°C: <1 % at 700°C: <2 %
Thermal Conductivity:	Perpendicular to Plane of the Plate: 0,3 W/mK 0,3 W/mK Along the Plane of the Plate: 3,0 W/mK 3,0 W/mK	Perpendicular to Plane of the Plate: 0,3 W/mK Along the Plane of the Plate: 3,0 W/mK
Thermal Expansion:	Perpendicular: 100 x 10 <sup>-6</sup> /°K Parallel: 10 x 10 <sup>-6</sup> /°K	Perpendicular: 100 x 10 <sup>-6</sup> /°K Parallel: 10 x 10 <sup>-6</sup> /°K